



Product/Process Change Notice - PCN 20_0133 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Assembly Transfer of Select PBGA Products and Conversion to CSP_BGA to STATS ChipPAC Korea

Publication Date: 26-Aug-2020

Effectivity Date: 17-Oct-2020 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Correct mold compound from KE-G2280TS (Low alpha) to Sumitomo G760SYA (Low Alpha).

Description Of Change:

Assembly site for PBGA is moving from STATS ChipPAC Singapore (STA) to existing qualified site STATS ChipPAC Korea (SK3). The Selected PBGA parts will be converted to CSP_BGA in STATS ChipPAC Korea (SK3). Change in Mold compound from Sumitomo G770 to Sumitomo G760SYA(Low alpha EMC for DSP products).

Existing qualified BOM in SK3 will be used.

Reason For Change:

STATS ChipPAC, Singapore (STA) issued a discontinuance notice to ADI to close their wirebonded products assembly by Dec 31, 2020.

ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, materials, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from different manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability:

No impact on form, fit and function.

Product Identification *(this section will describe how to identify the changed material)*

Parts assembled at SK3 will be identified by Assembly Lot number and Date Code

Summary of Supporting Information:

Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan

Supporting Documents

Attachment 1: Type: Qualification Plan

ADI_PCN_20_0133_Rev_A_001124_Qual Plan Summary for CSP_BGA at SK3 RevB.pdf

Attachment 2: Type: Detailed Change Description

ADI_PCN_20_0133_Rev_A_Material Set _CSP_BGA Transfer_Conversion.pdf

Attachment 3: Type: Package Outline Drawing

ADI_PCN_20_0133_Rev_A_Package Outline Drawing Summary.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (4)

ADSP-BF533 / ADSP-BF533SBBZ500	ADSP-BF533L / ADSP-BF533SBBZ400	ADSP-TS101S / ADSP-TS101SABZ2000	ADSP-TS101S / ADSP-TS101SABZ2100	
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Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	15-Jul-2020	17-Oct-2020	Initial Release.
Rev. A	26-Aug-2020	17-Oct-2020	Correct mold compound from KE-G2280TS (Low alpha) to Sumitomo G760SYA (Low Alpha).

Analog Devices, Inc.

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